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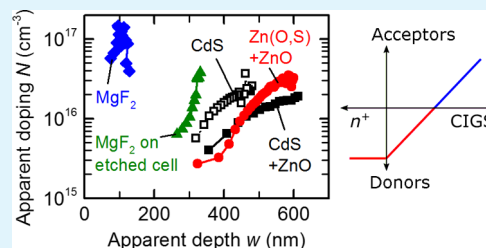
# Interdiffusion and Doping Gradients at the Buffer/Absorber Interface in Thin-Film Solar Cells

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**ABSTRACT:** An accurate determination of the net dopant concentration in photovoltaic absorbers is critical for understanding and optimizing solar cell performance. The complex device structure of multilayered thin-film solar cells poses challenges to determine the dopant concentration. Capacitance–voltage ( $C-V$ ) measurements of Cu(In,Ga)Se<sub>2</sub> thin-film solar cells typically yield depth-dependent apparent doping profiles and are not consistent with Hall measurements of bare absorbers. We show that deep defects cannot fully explain these discrepancies. We instead find that the space charge region capacitance follows the model of a linearly graded junction in devices containing a CdS or Zn(O,S) buffer layer, indicating that elemental intermixing at the buffer/window interface alters the dopant concentration within the absorber. For absorbers covered with MgF<sub>2</sub>,  $C-V$  measurements indeed agree well with Hall measurements. Photoluminescence measurements of Cu(In,Ga)Se<sub>2</sub> absorbers before and after deposition of a CdS layer provide further evidence for a significant reduction of the near-surface net dopant concentration in the presence of CdS. We thus demonstrate that interdiffusion at the absorber/buffer interface is a critical factor to consider in the correct interpretation of doping profiles obtained from  $C-V$  analysis in any multilayered solar cell and that the true bulk dopant concentration in thin-film devices might be considerably different.

**KEYWORDS:** doping profile, capacitance–voltage, Mott–Schottky, thin-film solar cells, diffusion



## 1. INTRODUCTION

Photovoltaic technologies play a crucial role for a clean and renewable generation of electricity. Solar cells based on high-quality single-crystalline semiconductors, for example, silicon or gallium arsenide, are generally most successful in terms of pure record power conversion efficiency.<sup>1</sup> In contrast, thin-film photovoltaic technologies emerged from the idea to reduce fabrication costs<sup>2</sup> and were shown to be superior in terms of energy payback time and carbon footprint.<sup>3,4</sup> Despite their intrinsically lower material quality, thin-film solar cells achieve remarkably high power conversion efficiencies on a laboratory scale. Recently, solar cells based on the ternary chalcopyrite semiconductor Cu(In,Ga)Se<sub>2</sub> (CIGS)<sup>5–7</sup> have demonstrated the highest efficiencies among all low-cost thin-film photovoltaic technologies with record efficiencies of up to 22.9%<sup>8,9</sup> on rigid substrates and of 20.4% using flexible substrates.<sup>10</sup> Efficiencies exceeding 22% have also been reported for thin-film devices based on CdTe<sup>11</sup> and perovskite<sup>12</sup> absorbers. Thin-film solar cells are complex multilayer structures.

Reliable experimental techniques to measure fundamental material properties of the semiconducting absorber layer and other constituent elements of the device are crucial to understand and optimize the performance of a solar cell. The net dopant concentration of the absorber layer, for example, significantly affects the recombination rate in the device and the width of the space charge region (SCR) at the charge-collecting p/n junction.<sup>13</sup> Accordingly, both open-circuit

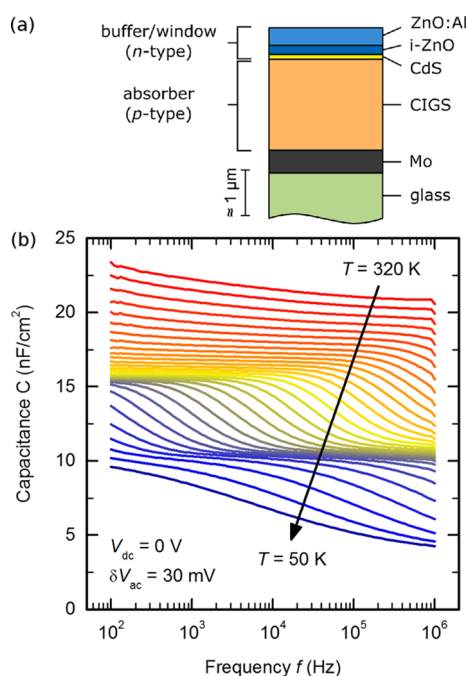
voltage and short-circuit current density of the solar cell directly depend on the bulk dopant concentration. Correct knowledge of the doping level, thus, is a prerequisite to model or simulate thin-film solar cells or indeed any other thin-film device. The doping level can be obtained experimentally from Hall measurements or capacitance–voltage ( $C-V$ ) measurements. Both methods are well established for bulk semiconductors<sup>13–16</sup> but are challenging to interpret in thin-film devices.<sup>17–19</sup> As a result, obtaining a correct description of the depth-dependent concentration of dopants in the absorber layer of a thin-film device requires particular care. In the present manuscript, we discuss CIGS devices in detail; similar effects are, however, likely to occur as well in CdTe solar cells and other thin-film devices containing heterojunctions.

On the one hand, thin-film solar cells consist of several thin layers with corresponding interfaces, as depicted on the top of Figure 1 for the example of a typical CIGS thin-film solar cell. This complex device geometry requires a complex electrical equivalent circuit<sup>20–24</sup> to interpret the measured capacitance and thus might have a strong impact on the extracted doping profiles. In particular, bias-dependent capacitance–voltage measurements always have to be regarded in relation to the frequency-dependent capacitance spectrum. On the other

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**Figure 1.** (a) Sketch of a typical CIGS thin-film solar cell processed on a glass substrate: a Mo back contact, a p-doped CIGS absorber layer, a CdS buffer layer, and an n-type window double layer (nonintentionally-doped “intrinsic” i-ZnO and Al-doped ZnO). The given scale is only approximate. (b) Experimental capacitance spectrum  $C(f)$  of a CIGS solar cell in a measured temperature range of 320–50 K, showing a main capacitance step from 15 down to 10 nF/cm<sup>2</sup> in a temperature range of 250–70 K and a capacitance freeze-out at the lowest temperatures.

Several common features are routinely observed in the electrical characterization of CIGS thin-film solar cells.

- At least one pronounced capacitance step in thermal admittance spectroscopy with an activation energy around 100 meV, similar to that shown in Figure 1, which has been termed the N1 signature.<sup>29</sup> It has traditionally been interpreted as the signature of a defect level either at the interfaces<sup>27,29</sup> or in the bulk.<sup>30</sup> Recently, an increasing number of publications link this capacitance step to transport phenomena in the bulk<sup>31,32</sup> or transport barriers at the interfaces.<sup>21,23,24,26,33–36</sup>
- A “U”-shaped depth-dependent doping profile,<sup>26,30,37–40</sup> with a minimum dopant concentration typically in the range of a few  $10^{15}$  cm<sup>-3</sup> for moderate applied bias and significantly higher dopant concentrations toward higher forward bias (“front”) and reverse bias (“back”). The increase toward forward bias is explained by minority carrier injection and parasitic resistances, whereas the increase toward reverse bias is typically attributed to the presence of deep defects.<sup>25</sup>

In a previous study,<sup>19,40</sup> we demonstrated that Hall measurements yield dopant concentrations significantly higher than that suggested by the standard interpretation of  $C-V$  measurements and we argued that transport barriers or defects are most likely not sufficient to explain this discrepancy. Furthermore, a different doping in films grown directly on glass compared to those grown on Mo could also be excluded by measuring a film grown on Mo and mechanically removed from the substrate. We rather proposed that cadmium indiffusion from the CdS buffer layer in these devices results in an increased donor concentration near the buffer/window interface, thus reducing the near-surface net dopant concentration compared to the strong p-type doping in the bulk. Such Cd indiffusion into CIGS has indeed been directly observed,<sup>41–45</sup> at least within a few tens of nanometers from the interface. The copper vacancy ( $V_{Cu}$ ) is expected to be a dominant acceptor in CIGS,<sup>46–49</sup> and substitutional Cd-on-Cu ( $Cd_{Cu}$ ) is predicted to form a donor in CIGS.<sup>50–52</sup> Furthermore, CdS can be doped p-type by replacing Cd with Cu.<sup>53</sup> Accordingly, Cd diffusion from CdS to available sites on the Cu lattice in CIGS, or vice versa, could lead to a substantially reduced net doping or even type inversion near the CIGS/CdS interface.

In this contribution, we present further insight into the electrical characterization of CIGS solar cells with particular focus on doping gradients in capacitance–voltage measurements. In Section 3, we discuss deep defects in CIGS and explore to which extent they might be responsible for gradients in the apparent doping profile. We review the impact of doping gradients on the bias dependence of the junction capacitance in Section 4 and compare our experimental data to different junction models. We find that elemental interdiffusion between the buffer layer and absorber indeed consistently explains our electrical measurements, which we verify in Section 5 by replacing the standard CdS/ZnO buffer/window stack with alternative buffers and interfaces. We also provide a short update on our previous Hall measurements of CdS-coated absorbers grown on glass. Our electrical studies are complemented and confirmed by photoluminescence (PL) measurements of bare and CdS-covered absorbers in Section 6. Our results provide further support for interdiffusion as a

hand, carrier traps and recombination centers in the form of electronic defects might be present within the active CIGS absorber layer or at the buffer/absorber interface. Even at high frequencies, where capacitive contributions from such defects are typically negligible, charges stored in the defects can still affect the experimental capacitance–voltage relations if the defect level crosses the Fermi level somewhere in the absorber. This adds a bias-dependent contribution of defect states to the true concentration<sup>25</sup> of shallow dopants in the absorber.

In the standard approach to obtain the absorber dopant concentration from a  $C-V$  measurement, the effective dopant concentration is calculated from the slope of the inverse squared capacitance  $C^{-2}$  as a function of applied bias voltage  $V$  (“Mott–Schottky plot”).<sup>15</sup> The corresponding apparent depth is calculated from the inverse capacitance assuming a parallel plate capacitor between both edges of the SCR. Note that the SCR is typically assumed to only extend into the p-type absorber because of the (assumed) high n-type doping of the buffer/window layers. In addition to this fundamental assumption, the effect of additional layers and interfaces in the device structure is usually not taken into account. Although some authors do consider the contribution of an intrinsic interlayer to the SCR width, for example, the buffer layer in CIGS solar cells,<sup>26–28</sup> further effects of the n-doped side are neglected. Most importantly, however, the standard interpretation of  $C-V$  measurements relies on the assumption of 99 sharp and well defined “step-like” interfaces, that is, no intermixing of adjacent materials should occur within the device.

163 critical factor for the correct interpretation of doping profiles  
164 obtained from  $C$ – $V$  analysis.

## 2. EXPERIMENTAL DETAILS

165 We study polycrystalline CIGS thin-film absorbers, which are grown  
166 on Mo-coated soda-lime glass in a three-stage coevaporation process  
167 with varying Cu and Ga contents and incorporating a double Ga  
168 gradient. For the electrical measurements shown in this manuscript,  
169 we have exemplarily chosen absorbers with copper content of  $[Cu]/$   
170  $([Ga] + [In]) \approx 0.98$ – $0.99$  and average gallium content of  $[Ga]/$   
171  $([Ga] + [In]) \approx 0.28$ – $0.37$  as determined from energy-dispersive X-  
172 ray (EDX) measurements. Despite the Cu content close to unity  
173 estimated from EDX, these absorbers clearly show PL peaks  
174 characteristic for compensated Cu-poor material. The set of samples  
175 shown in this manuscript was chosen to minimize the impact of  
176 potential near-surface vacancy compounds in highly Cu-deficient  
177 absorbers and because these absorbers resulted in the highest solar  
178 cell efficiencies of 16–18%. We obtain comparable trends also for  
179 absorbers with different compositions, in particular for a range of Cu  
180 contents in Cu-poor samples and also for samples without Ga.  
181 Absorbers grown under Cu excess (“Cu-rich”) were etched in a  
182 potassium cyanide (KCN) solution to remove  $Cu_xSe$  secondary  
183 phases developed under Cu-rich growth conditions and thus result in  
184 nominally stoichiometric absorbers. All samples contain Na and to a  
185 certain extent K, from the glass substrate, but have not received an  
186 additional alkali postdeposition treatment.

187 Standard solar cells have a CdS buffer layer deposited by chemical  
188 bath deposition (CBD) for 5–6 min at 67 °C (2 mM  $CdSO_4$ , 50 mM  
189 thiourea, 1.5 M  $NH_4OH$ ). The thickness is estimated to be 40–50  
190 nm from typical growth rates. Alternatively, Zn(O,S) is deposited by  
191 CBD for 6 min at 75 °C (0.1 M  $ZnSO_4 \cdot 7H_2O$ , 0.4 M thiourea, 2 M  
192  $NH_4OH$ , and 0.22 M  $H_2O_2$  30%, recipe adapted from refs,<sup>54,55</sup>  
193 estimated thickness 20–35 nm). On top of the buffer layer, we  
194 deposit an rf-sputtered i-ZnO/ZnO:Al double window layer and a Ni/  
195 Al front contact grid defined by electron beam evaporation through a  
196 shadow mask. Solar cells with an active area of 0.2–0.5  $cm^2$  are  
197 defined by mechanical scribing and achieve efficiencies above 16% at  
198 room temperature under 1 sun illumination.

199 For electrical measurements, samples are mounted in the dark in a  
200 closed-cycle cryostat at a base pressure below  $10^{-3}$  mbar. The sample  
201 temperature is measured with a Si diode sensor glued onto an  
202 identical glass substrate beside the solar cells. The device conductance  
203 and capacitance are recorded with an LCR meter in a maximum  
204 frequency range of  $f = 20$  Hz to 2 MHz with a controlled ac voltage  
205 amplitude of  $\delta V_{ac} = 30$  mV rms, assuming a standard parallel  
206 equivalent circuit model (“ $G_p$ – $C_p$  model”). We use the measured dc  
207 voltage across the terminals connecting the solar cell for all voltage-  
208 dependent measurements to exclude artifacts because of the internal  
209 resistance of the LCR meter. In Section 5, we use a deconvolution of  
210 the frequency-dependent impedance spectrum based on the serial  
211 electrical equivalent circuit consisting of two  $R$ – $C$  elements  
212 representing the buffer layer and main junction, respectively. This  
213 approach is detailed in ref 23.

214 For calibrated PL measurements, the samples are excited by the  
215 514.5 nm line of an argon ion laser at room temperature. The emitted  
216 PL is collected by off-axis parabolic mirrors, redirected into a 303 mm  
217 spectrograph, and recorded by an InGaAs-array detector. Spectral  
218 correction is applied using a calibrated halogen lamp. The beam  
219 diameter and laser power are measured with a charge-coupled device  
220 camera and power meter, respectively, to calibrate the photon flux.  
221 The samples are cooled to a temperature of 10 K in a He-flow cryostat  
222 for low-temperature measurements. Time-resolved PL measurements  
223 are performed with a pulsed laser diode at 638 nm wavelength and  
224 100 ps pulse width. The PL transients are recorded with a time  
225 resolution of approximately 400 ps with a near-infrared photo-  
226 multiplier tube employing time-correlated single photon counting.  
227 Storage of bare absorbers in air reduces both quasi-Fermi level  
228 splitting<sup>56</sup> and lifetime, which can be reversed by cyanide etching.  
229 Thus, cyanide etching is necessary for bare absorbers before PL

measurements. Absorbers covered with CdS in contrast show a 230  
constant quasi-Fermi level splitting over many months.<sup>56</sup> 231

## 3. EFFECT OF DEEP DEFECTS ON THE DOPING PROFILE

232 Electronic defects within the SCR modify the capacitance–  
233 voltage relation and might thus lead to a misinterpretation of  
234 the experimental apparent doping profiles. At angular  
235 excitation frequencies well above the inverse response time  
236 of a given defect state, this defect no longer responds to the ac  
237 voltage modulation and remains in the same charge state. This  
238 causes the direct contribution of defect states to the device  
239 capacitance to vanish at high frequencies. Figure 1 shows a  
240 typical zero-bias capacitance spectrum of a Cu-poor CIGS  
241 solar cell for sample temperatures in a range of 320–50 K.  
242 First, we have to establish which features in the capacitance  
243 spectrum are actually related to deep defects. From low to high  
244 temperatures, we observe the following features.

245 **3.1. Freeze-Out.** The low-temperature capacitance step ( $C$   
246  $\approx 10$ – $4$  nF/ $cm^2$ ) is clearly related to a freeze-out of the  
247 absorber because the capacitance drops to the geometrical  
248 capacitance  $C = \epsilon_0 \epsilon_r / d$  of the absorber layer with a thickness of  
249  $d = 2.3$   $\mu m$ , assuming a relative dielectric permittivity  $\epsilon_r = 10$ .  
250 It is thus not relevant for the present discussion. 251

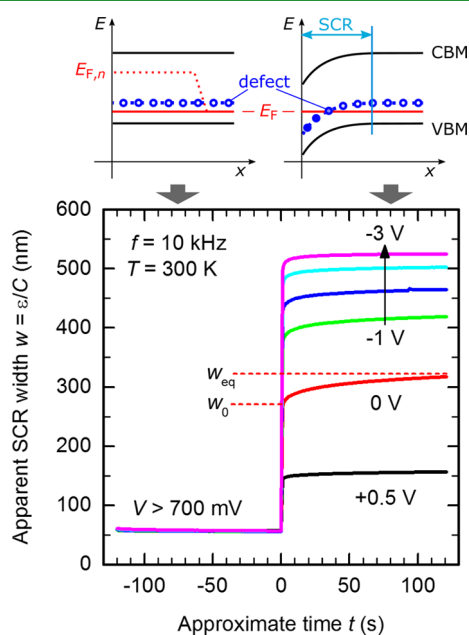
252 **3.2. Main Capacitance Step (“N1”).** The main  
253 capacitance step ( $C \approx 15$ – $10$  nF/ $cm^2$ ) in a temperature  
254 range of 250–70 K agrees with the N1 signature<sup>29</sup> commonly  
255 observed for CIGS solar cells and could in principle be related  
256 to deep defects. If this was the case, these defects could follow  
257 the ac excitation over the full experimental frequency range for  
258  $T > 250$  K and accordingly would always contribute to the  
259 capacitance near room temperature. However, on the basis of  
260 refs,<sup>23,24,36</sup> we instead attribute this capacitance step to a  
261 transport barrier or interfacial/buffer layer in our devices.

262 **3.3. Slow Defects?** The slight capacitance dispersion at the  
263 highest temperatures above the main capacitance step might be  
264 caused by tail states at the band edges<sup>57</sup> but might also indicate  
265 the presence of slow defect states in the bulk or at the interface.  
266 “Slow” in this context refers to a capacitance step with  
267 inflection frequency well below the experimental frequency  
268 range.

269 According to these observations, we only expect slow defect  
270 levels that do not follow the ac excitation in a  $C$ – $V$   
271 measurement near room temperature. Nevertheless, the  
272 charges stored in these defects at a given applied dc bias  
273 voltage will differ from the zero-bias case, unless the defect  
274 level is energetically far away from the Fermi level everywhere  
275 in the SCR. The potential distribution across the device is  
276 described by the Poisson equation, which links the potential to  
277 the total charge density including carriers in the bands, ionized  
278 dopants, and charged defects. Despite a negligible direct  
279 capacitive contribution, charged defects thus modify the band  
280 bending in the SCR and consequently also alter the SCR  
281 capacitance. This results in a “stretch-out” of the capacitance–  
282 voltage curve along the voltage axis, and the apparent doping  
283 concentration obtained from the Mott–Schottky plot  
284 increases.<sup>15,25</sup> For sufficiently high ac frequencies or temper-  
285 atures, the only impact of defects on the doping profile thus  
286 originates from the slow variation of the dc bias voltage, which  
287 allows the defect charges to equilibrate at each measurement  
288 point on the bias voltage ramp. We indeed observe a  
289 measurable difference in the doping profiles depending on  
290 the voltage sweep rate used in the experiment (not shown)

291 here), which suggests an influence of deep defects on the  
 292 device capacitance. We thus investigate the time-dependence  
 293 of the measured capacitance in response to changes in dc bias  
 294 voltage to quantify the impact of deep defects on the  
 295 capacitance measurement.

296 Because we only expect slow defect levels, we are fairly  
 297 unrestricted in our choice of measurement frequency. Here, we  
 298 have chosen an ac frequency of 10 kHz to avoid artifacts due to  
 299 series resistance, which increase with frequency. We study the  
 300 time-evolution of the SCR width due to charging or  
 301 discharging of defects by the following method: the sample  
 302 is kept at a forward bias of  $\approx 700$  mV, comparable to the open-  
 303 circuit voltage  $V_{oc}$  under 1 sun illumination, for at least 120 s.  
 304 The capacitance is continuously monitored to verify that a  
 305 saturation value is reached after this time. This procedure  
 306 ensures that the device is in a well-defined steady state in  
 307 forward bias with all relevant trap levels above the Fermi level  
 308 of the bulk majority carriers, as depicted by the top left sketch  
 309 in Figure 2. The bias voltage is then set to the voltage of



**Figure 2.** Top: Schematic sketch of the conduction band minimum and valence band maximum as a function of depth below the CIGS/CdS interface, with a defect level and its occupation indicated by blue circles, in forward bias (left) and in equilibrium (right). The red lines represent the majority (quasi-)Fermi level ( $E_F$ , solid line) and minority quasi-Fermi level ( $E_{F,n}$ , dotted line). Bottom: Evolution of the apparent SCR width  $w = \epsilon_0 \epsilon_r / C$ , with  $\epsilon_0 = 10$  as a function of time after keeping the device under forward bias of +700 mV immediately before applying a set bias voltage between +0.5 V and  $-3.0$  V, as indicated in the graph. The red dashed lines exemplarily mark the initial ( $w_0$ ) and final ( $w_{equiv}$ ) SCR width at 0 V.

310 interest at  $t = 0$  and the capacitance is monitored for at least  
 311 120 s. Depending on the chosen bias voltage and thus band  
 312 bending in the SCR, a bulk defect level might now cross the  
 313 Fermi level within the SCR, as shown by the top right sketch in  
 314 Figure 2. Charging or discharging of these defects will then  
 315 cause a change in the SCR width with time, which manifests as  
 316 a capacitance transient in the experiment. After the measure-  
 317 ment, the device is allowed to relax at zero bias for a few  
 318 minutes; then, this procedure—prebiasing at +700 mV  
 319 followed by a change in bias voltage—is repeated for a

different bias voltage. Note that our admittance setup is not  
 equipped to measure precise time-resolved capacitance  
 transients, and the recorded transients are limited to a time  
 resolution of approximately 1 s. This uncertainty does not  
 influence the analysis in our study as we do not take the  
 quantitative decay time constant into account.

Figure 2 shows a set of capacitance transients for different  
 applied bias voltages between +0.5 V and  $-3$  V and a sample  
 temperature of  $T = 300$  K. We plot the corresponding apparent  
 SCR width  $w = \epsilon_0 \epsilon_r / C$  rather than the capacitance  $C$  to  
 emphasize that the defects at the chosen frequency of 10 kHz  
 mainly act on the potential and thus  $w$ , rather than directly on  
 the capacitance  $C$ . Note that any intrinsic layer, for example, a  
 depleted buffer layer, would add a constant width  $w_i$  to the  
 SCR width, independent of the bias voltage. Throughout this  
 paper, we assume a relative dielectric permittivity of  $\epsilon_r = 10$  for  
 CIGS but our discussion does not depend on the exact value.

For  $t < 0$ , all curves in Figure 2 coincide as expected. Minor  
 differences in capacitance correlate with variations of a few mV  
 in the actual applied bias voltage. Note that the capacitance in  
 forward bias shows an exponential voltage dependence because of  
 carrier injection, and thus, small variations in bias voltage  
 lead to a large spread in capacitance values.

When a bias voltage lower than the open-circuit voltage  $V_{oc}$   
 is applied at  $t = 0$ , the apparent SCR width increases  
 instantly—within our measurement resolution of roughly 1 s—  
 to an initial value  $w_0$  and then slowly increases further to a  
 saturation value  $w_{equiv}$ . These values are indicated in Figure 2  
 for the example of the zero-bias transient. We interpret the  
 initial values of the SCR width  $w_0$  and capacitance  $C_0$  as the  
 ideal capacitance of the SCR in the absence of deep defects  
 because slow defects did not yet have sufficient time to change  
 their charge state and thus do not contribute to the capacitance  
 at all. After some time, these defects equilibrate and additional  
 charges localized in the defects result in an expansion of the  
 SCR to the final width  $w_{equiv}$  in steady-state conditions. Taking  
 the initial value  $C_0$  at each bias voltage thus allows us to  
 construct an experimental  $C$ – $V$  curve representative of a  
 device without any deep defects. In this interpretation, we have  
 neglected defects with response times faster than 1 s, for which  
 we would not be able to resolve the capacitance transient, but  
 above a few milliseconds corresponding to an inflection  
 frequency at the lower limit of our experimental frequency  
 range (typically 20–100 Hz). As discussed above, we, however,  
 do not expect such defects to be present in our devices in  
 significant concentrations because of the small capacitance  
 dispersion at  $T = 300$  K.

It is worth pointing out that the slow defect response  
 observed in the capacitance transients is not related to  
 metastabilities<sup>5</sup> in the CIGS absorber. For a given bias voltage,  
 we always obtain the same capacitance transient, independent  
 of biasing or illumination history of the sample. This means  
 that the capacitance only changes because of the slow capture  
 and emission of charge carriers, but the nature of the defects is  
 not altered by light soaking or by applying a bias voltage. In a  
 different study<sup>23</sup> on comparable absorbers, we also did not  
 observe any impact of the wavelength of illumination;  
 particularly, we did not find any change of electronic or  
 transport properties under illumination in the absence of blue  
 light, as has been reported for certain buffer/absorber  
 combinations earlier.<sup>58</sup>

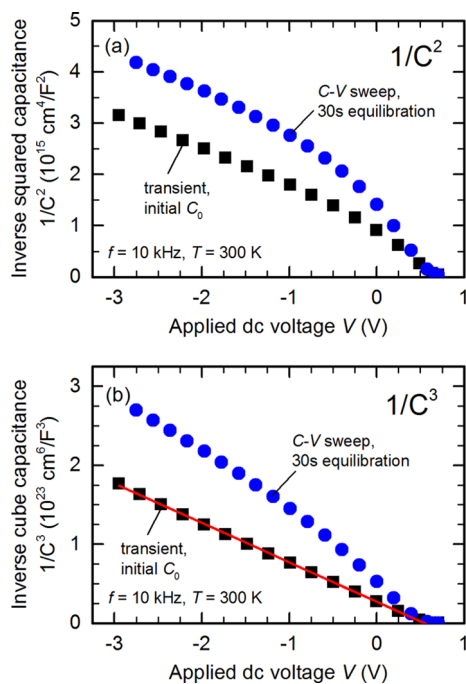
#### 4. DOPING GRADIENTS IN CAPACITANCE–VOLTAGE MEASUREMENTS

381

382 We can now compare two different sets of  $C$ – $V$  data of the  
383 same sample to investigate to which extent apparent doping  
384 gradients in CIGS devices are caused by deep defect  
385 contributions:

- 386 • The initial capacitance  $C_0$  of the capacitance transient as  
387 described above, which we identify with the ideal SCR  
388 capacitance of a hypothetical device without deep  
389 defects and
- 390 • a conventional  $C$ – $V$  measurement at a frequency of 10  
391 kHz, where the bias voltage is incrementally decreased  
392 from forward to reverse bias in steps of 100 mV, with a  
393 wait time of 30 s after each voltage step, which thus  
394 includes the effects of deep defects on the SCR width.

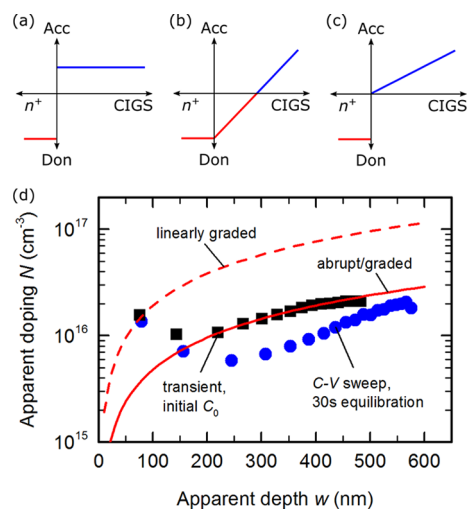
395 **Figure 3a** shows the Mott–Schottky plots, that is, inverse  
396 squared capacitance versus applied dc voltage, for the transient



**Figure 3.** Voltage dependence of (a) the inverse squared capacitance  $C^{-2}(V)$  and (b) the inverse cube capacitance  $C^{-3}(V)$  at  $T = 300$  K and  $f = 10$  kHz, obtained from a standard capacitance–voltage sweep with equilibration time of 30 s (blue circles) and from the initial SCR capacitance  $C_0$  extracted from the capacitance transients (black squares). The red solid line in part (b) is a linear fit to the data.

397 data (black squares) and conventional  $C$ – $V$  sweep (blue  
398 circles). The corresponding apparent doping profiles are  
399 shown in **Figure 4d** (solid symbols).

400 As expected, the Mott–Schottky plots mirror the trend seen  
401 in the capacitance transients: in the conventional  $C$ – $V$   
402 measurement, charged slow defects increase the SCR width  
403 and lead to a clearly nonlinear Mott–Schottky plot. Note that  
404 the exact bias dependence then depends on the voltage sweep  
405 rate (not shown here). In contrast, the ideal SCR capacitance  
406 obtained from the starting value of the capacitance transients  
407  $C_0$  yields a much flatter doping profile. At least some part of  
408 the apparent depth dependence of typical doping profiles in  
409 CIGS devices is thus indeed related to the presence of deep  
410 defects in the SCR or at the CdS/CIGS interface. Note,



**Figure 4.** (a–c) Net acceptor (blue) and donor (red) concentrations near the interface between p-type CIGS bulk and n-type buffer/window layers for an (a) abrupt constant profile, (b) linearly graded profile, and (c) abrupt graded profile. For clarity, the n-type doping is drawn lower than typically assumed and any intrinsic interlayers are ignored. (d) Apparent dopant concentration  $N$  as a function of apparent depth  $w$  obtained from the Mott–Schottky plots of a standard  $C$ – $V$  sweep (blue circles) and the initial SCR capacitance of the capacitance transients (black squares). The red lines are reconstructed doping profiles for an assumed linearly graded profile [as in (b), dashed line] or abrupt graded profile [as in (c), solid line] with a slope parameter of  $dC^{-3}/dV = -5 \times 10^{22} (\text{F}/\text{cm}^2)^{-3}/\text{V}$ .

however, that even the “ideal” capacitance does not obey a  
linear Mott–Schottky relation and thus indicates an  
inhomogeneous dopant concentration.

**4.1. Fundamental Junction Models.** So far, we have not  
addressed the implications of a potentially inhomogeneous  
doping profile on the analysis of capacitance–voltage measure-  
ments. Relations between various depth profiles of dopant  
concentration and their respective capacitance–voltage curves  
are discussed by van Opdorp in ref 59. On the basis of his  
work, we will summarize the relations relevant for the present  
discussion. For an arbitrary doping profile, the voltage drop  
 $V$  is integrated over the SCR width  $w$  according to

$$dV = -\frac{q}{\epsilon} N(w) w \, dw \quad (1)$$

where  $q$  is the elementary unit charge,  $\epsilon = \epsilon_0 \epsilon_r$  is the dielectric  
permittivity of the semiconductor, and  $N(w)$  is the apparent  
effective doping concentration given by

$$N(w) = \left[ \frac{1}{N_A(x_p)} + \frac{1}{N_D(x_n)} \right]^{-1} \quad (2)$$

where  $N_A(x_p)$  and  $N_D(x_n)$  are the net acceptor (donor)  
concentrations at the edges  $x_p$  and  $x_n$  of the SCR on the p- and  
n-doped side at the applied voltage  $V$ , respectively, and the  
total SCR width is given by  $w = x_n + x_p$ . The capacitance  $C$  at a  
given voltage is then obtained by substituting  $C = \epsilon/w$ . It is  
generally not possible to unambiguously deduce the correct  
physical acceptor or donor profiles as a function of depth from  
a simple  $C$ – $V$  measurement alone because it requires  
knowledge of  $x_n$ ,  $x_p$ ,  $N_A(x_p)$ , and  $N_D(x_n)$  for each bias  
voltage.<sup>59</sup> Nevertheless, information about the qualitative  
shape of the apparent doping profile can be obtained from

439 the exponent  $x$  of a linear  $C^{-x}(V)$  relation, which arises from  
 440 the depth-dependence of the apparent doping concentration  
 441  $N(w)$  in eq 1; although the exact values of  $N_{A,D}(x)$  cannot be  
 442 determined, it is possible to distinguish whether the net dopant  
 443 concentration changes with depth or not.

444 Three exemplary doping profiles relevant for the present  
 445 discussion are sketched in Figure 4a–c. The constant doping  
 446 model in Figure 4a represents the standard model used in most  
 447 discussions, where the net dopant concentrations at the n- and  
 448 p-doped sides are assumed to be uniform throughout the depth  
 449 of the device with a step-like junction in-between. In this case,  
 450  $N(w)$  is constant and integration of eq 1 yields

$$451 \quad V_D - V = \frac{qN}{2\epsilon} \left( \frac{\epsilon}{C} \right)^2 \quad (3)$$

452 where the integration constant  $V_D$  is an offset voltage related to  
 453 the built-in potential at the junction. The inverse square  
 454 capacitance thus yields a straight line as a function of voltage,  
 455 which explains the prominence of the Mott–Schottky plot in  
 456  $C-V$  analysis. If furthermore the donor concentration in the  
 457 buffer/window layers is assumed to far exceed the CIGS  
 458 acceptor concentration, the effective dopant concentration in  
 459 eq 2 approximately equals the CIGS net acceptor concen-  
 460 tration. The inverse slope of the Mott–Schottky plot  $C^{-2}(V)$  is  
 461 then directly proportional to the approximate CIGS absorber  
 462 dopant concentration.

463 Figure 4b represents a linearly graded doping profile, where  
 464 the net donor and acceptor concentrations increase linearly  
 465 with a gradient of  $a = dN/dx$  with respect to distance  $x$  from  
 466 the junction. Thus,  $N_A(x_p) = N_D(x_n) = aw/2$  at the edges of  
 467 the SCR. Integration then yields

$$468 \quad V_D - V = \frac{qa}{12\epsilon} \left( \frac{\epsilon}{C} \right)^3 \quad (4)$$

469 where the denominator of the prefactor contains a factor of 3  
 470 because of the cubic dependence on capacitance and a factor of  
 471 4 from  $N(w) = aw/4$  according to eq 2. The abrupt graded  
 472 profile in Figure 4c represents an intermediate case between  
 473 the two former extremes; here, the electronic junction  
 474 coincides with the absorber/buffer interface, and only one  
 475 side of the junction exhibits a gradient of the dopant  
 476 concentration. For sufficiently high doping in the n-doped  
 477 side, the SCR mainly extends into the linearly graded p-doped  
 478 side of the junction ( $w \approx x_p$ ), and the capacitance–voltage  
 479 relation is given by

$$480 \quad V_D - V = \frac{qa}{3\epsilon} \left( \frac{\epsilon}{C} \right)^3 \quad (5)$$

481 The abrupt graded profile, eq 5, differs from the linearly  
 482 graded profile, eq 4, only by a factor of 4 because now  $N(w) \approx$   
 483  $N_A(x_p) \approx aw$ .

484 For both types of graded profiles, a plot of the inverse cube  
 485 capacitance  $1/C^3$  versus applied voltage is thus expected to  
 486 yield a straight line. A constant dopant concentration  
 487 sufficiently far away from the junction, as pictured here for  
 488 the highly n-doped window layer, has no effect on the  $C-V$   
 489 relation if the SCR is always confined to the linearly graded  
 490 section of the doping profile for the full range of bias voltages  
 491 employed in the measurement. Note that linearly graded  
 492 models are also good approximations for technologically more  
 493 relevant exponential diffusion profiles, which can locally be  
 494 approximated by a linear gradient.<sup>59</sup> An abrupt graded model,

on the other hand, might be applicable if the CIGS absorber 495  
 always remains p-doped at the surface and the CdS buffer is 496  
 unaffected by interdiffusion of Cd and Cu or always located 497  
 fully within the SCR. 498

**4.2. Comparison with Experiment.** Figure 3b shows that 499  
 we indeed observe a nearly perfectly linear voltage-dependence 500  
 of the inverse cube capacitance obtained from the capacitance 501  
 transients (ideal SCR, black squares in Figure 3b), in 502  
 accordance with the predictions for a graded doping profile. 503  
 From a linear fit to the data (solid red line), we deduce a slope 504  
 parameter of  $dC^{-3}/dV = -(5.0 \pm 0.1) \times 10^{22} \text{ (F/cm}^2\text{)}^{-3}/V$ . 505  
 This value corresponds to a doping gradient of  $a = 1.9 \times 10^{14}$  506  
 $\text{cm}^{-3}/\text{nm}$  for a linearly graded profile, eq 4, and a four times 507  
 lower gradient  $a = 4.8 \times 10^{13} \text{ cm}^{-3}/\text{nm}$  for an abrupt/graded 508  
 profile, eq 5. Reconstructed acceptor concentration profiles in 509  
 the CIGS absorber based on this fit are shown by the red lines 510  
 in Figure 4d as a function of the physical distance from the p/ 511  
 n-junction for the two different graded doping models. 512

For the abrupt/graded profile [Figure 4c], assuming a highly 513  
 n-doped window layer, the apparent SCR width roughly 514  
 coincides with the physical depth of the depletion region edge 515  
 $x_p$  within the absorber, resulting in a one-sided junction. For 516  
 such a one-sided junction, the depth-dependent effective 517  
 dopant concentration can be derived from the local slope of a 518  
 Mott–Schottky plot  $C^{-2}(V)$  around each bias voltage. As 519  
 expected, the reconstructed abrupt/graded profile (solid red 520  
 line in Figure 4d) thus coincides with the apparent doping 521  
 profile obtained from a Mott–Schottky plot (black squares in 522  
 Figure 4d). This implies that the exact junction model is not 523  
 relevant for the interpretation of a  $C-V$  measurement as long 524  
 as the junction can be regarded as one-sided. Note that the 525  
 blue circles in Figure 4d are not comparable because this 526  
 doping profile includes the impact of slow defect states on the 527  
 $C-V$  relation, as discussed in Section 3. All models discussed 528  
 here are only valid in sufficient reverse bias, and thus, 529  
 differences for small apparent depth values should also be 530  
 neglected. 531

In contrast to the abrupt/graded case, the assumption of a 532  
 one-sided junction is no longer valid for a linearly graded 533  
 junction (Figure 4b). The SCR extends significantly into both 534  
 the n- and p-doped side and is in fact distributed equally 535  
 between both sides for an ideal linearly graded junction with 536  
 the same dopant gradient in the n- and p-type sides. 537  
 Accordingly, the experimental apparent doping profile under- 538  
 estimates the true absorber doping profile by a factor of 4 as 539  
 discussed in the derivation of eq 4, a factor of 2 for the effective 540  
 dopant concentration [ $N_A(x_p) = N_D(x_n)$  in eq 2], and a further 541  
 factor of 2 because the distance of either SCR edge from the 542  
 junction is just half the total SCR width. Accordingly, the 543  
 reconstructed doping profile for the linearly graded junction 544  
 (dashed red line in Figure 4d) implies dopant concentrations 545  
 larger than expected from the standard Mott–Schottky analysis 546  
 assuming a one-sided step junction. Remarkably, the linearly 547  
 graded junction model for this particular sample is consistent 548  
 with a bulk dopant concentration of approximately  $10^{17} \text{ cm}^{-3}$  549  
 expected from Hall measurements<sup>40</sup> on comparable absorbers. 550

The linear voltage-dependence of the inverse cube 551  
 capacitance shown in Figure 3b presents a compelling 552  
 argument for a graded junction. Note that based on these 553  
 $C-V$  measurements alone, we cannot differentiate between an 554  
 abrupt and linearly graded junction according to Figure 4b or 555  
 4c, that is, whether the p/n junction is located at the absorber/ 556  
 buffer interface or within the CIGS absorber. This distinction, 557

558 however, becomes critical when trying to reconcile the low  
559 experimental doping concentrations of a few  $10^{16} \text{ cm}^{-3}$  derived  
560 from  $C-V$  measurements with much higher values around  $10^{17}$   
561  $\text{cm}^{-3}$  obtained by Hall measurements. Because doping profiles  
562 extracted from a Mott–Schottky plot underestimate the true  
563 physical dopant concentration for linearly graded profiles  
564 (dashed red line in Figure 4d), a buried junction within the  
565 CIGS absorber due to an (approximately) linearly graded  
566 doping profile could nicely explain the stark differences  
567 between  $C-V$  and Hall measurements.

568 For the sample shown in Figure 4, the two different  
569 scenarios are as follows.

- 570 • Assuming a linearly graded profile, the experimental  
571 apparent dopant concentration of roughly  $2 \times 10^{16} \text{ cm}^{-3}$   
572 in high reverse bias (black squares in Figure 4d)  
573 corresponds to an *actual* net dopant concentration of up  
574 to  $8 \times 10^{16} \text{ cm}^{-3}$  at the corresponding apparent depth,  
575 in good agreement with Hall results.
- 576 • For an abrupt/graded profile, the apparent doping  
577 approaches values close to  $10^{17} \text{ cm}^{-3}$  only in a depth of 2  
578  $\mu\text{m}$  because of the low gradient of  $a = 4.8 \times 10^{13} \text{ cm}^{-3}/$   
579  $\text{nm}$ . The doping gradient in this case would extend  
580 through almost the entire CIGS thin film, which has a  
581 thickness of 2–2.5  $\mu\text{m}$  determined by cross section  
582 scanning electron microscopy.

583 On the basis of this comparison, we find that a linearly  
584 graded doping profile with a buried junction is the most  
585 natural explanation to reconcile the differences in doping level  
586 between  $C-V$  and Hall measurements because  $C-V$  measure-  
587 ments would underestimate the real doping density by a factor  
588 of up to 4. Even if we assume an abrupt/graded doping profile,  
589 where  $C-V$  measurements would in principle yield the correct  
590 dopant concentration, the doping level deep within the  
591 absorber would still exceed the near-surface dopant concen-  
592 tration within the SCR accessible by  $C-V$  measurements.

593 Experimentally, however, the apparent doping profile is only  
594 accessible in  $C-V$  in a limited depth range, given by the  
595 location of the SCR edges for various bias voltages. Thus, we  
596 cannot determine the net dopant concentration deep within  
597 the bulk from  $C-V$  and can only assume that it will level off at  
598 a dopant concentration close to that measured in Hall  
599 experiments. By the same reasoning, we would not be able  
600 to directly resolve any differently-doped, for example, intrinsic  
601 or highly  $p^+$ -doped, interlayers located in close proximity to the  
602 electronic junction. Note that such interlayers would, however,  
603 affect the extrapolated built-in potential, which could explain  
604 why the linear fit in Figure 3b intercepts the voltage axis more  
605 than 100 meV below the 1 sun open-circuit voltage of the  
606 device. The different doping models sketched in Figure 4a–c  
607 thus have to be regarded as schematic classifications only.  
608 From the presented  $C-V$  measurements, we thus conclude  
609 that a doping gradient exists in CIGS solar cells, with reduced  
610 net dopant concentration toward the buffer/window interface  
611 and potentially inverted n-type near-surface region within the  
612 absorber. It is, however, unlikely that a perfectly linear doping  
613 gradient throughout the full SCR forms in a real device.

## 5. COMPARING DIFFERENT BUFFER LAYERS

614 The preceding discussion indicates that doping gradients  
615 indeed exist in CIGS devices. On the basis of previous  
616 results,<sup>40</sup> such doping gradients could be caused by Cd in-  
617 diffusion and accordingly should be absent in devices where

the CdS buffer layer is replaced by an alternative Cd-free buffer  
layer. We compare four different samples, which have been  
processed from pieces of the same substrate. All samples thus  
share an identical absorber but differ in the buffer/window  
stacks used. Their respective buffer/window stacks are as  
follows:

1. CBD-CdS
2. CBD-CdS with i-ZnO/ZnO:Al,
3. CBD-Zn(O,S) with i-ZnO/ZnO:Al,
4.  $\text{MgF}_2$ , and
5.  $\text{MgF}_2$  after etching the CdS/ZnO from sample 2.

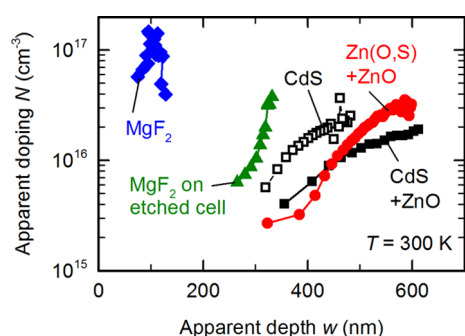
The CdS and Zn(O,S) buffer layers are deposited by CBD,  
whereas  $\text{MgF}_2$  with a nominal thickness of 50 nm is deposited  
by electron beam evaporation. For sample 5, the CdS/i-ZnO/  
ZnO:Al stack is etched from a piece of sample 2 in diluted  
hydrochloric acid (HCl), and the etched surface is then  
covered with  $\text{MgF}_2$ . Note that samples with the  $\text{MgF}_2$  layer did  
not receive any ZnO layers on top of  $\text{MgF}_2$ , neither did sample  
1 with only a CdS layer.

In addition to electrical measurements, we performed  
secondary ion mass spectrometry (SIMS) on all devices.  
Because of the rough surface and the presence of grain  
boundaries, however, these SIMS measurements are not  
conclusive at the moment. In fact, already very small quantities  
below 10 ppm of electrically active donor defects, compared to  
approximately  $4 \times 10^{22} \text{ cm}^{-3}$  total atoms in CIGS, are required  
to already fully compensate a bulk net acceptor concentration  
of  $10^{17} \text{ cm}^{-3}$ . It is unlikely that such small concentrations could  
be detected reliably by available depth- and element-specific  
experimental techniques such as SIMS or atom probe  
tomography.

The distinctly different buffer/window stacks in the five  
different samples might cause artifacts in the  $C-V$  analysis  
because of their impact on the device impedance. We thus use  
a serial connection of two circuit elements representing the  
junction and buffer/window stack, respectively, each consisting  
of a parallel capacitance and conductance, to extract the  
junction capacitance at each bias voltage from the correspond-  
ing frequency-dependent impedance.<sup>23</sup> For devices with a CdS  
or Zn(O,S) buffer layer, we find that this approach is not  
necessary for room-temperature measurements because the  
conductivity of the buffer layer is high and only affects the  
device impedance at lower temperatures. For the less  
conductive  $\text{MgF}_2$  layers, on the other hand, the main  
capacitance step is already visible at room temperature. As  
expected,<sup>23</sup> our circuit analysis results in doping profiles in  
agreement with standard  $C-V$  measurements at low  
frequencies below the capacitance step. Measurements at  
high frequencies above the capacitance step, however, are  
shifted to lower absolute values of dopant concentration and  
higher SCR width, although they result in a qualitatively similar  
depth dependence. The apparent depth-dependent doping  
profiles at a temperature of 300 K, obtained from the circuit  
analysis described above, are shown in Figure 5 for all five  
devices. Only the reverse-bias region ( $V < 0 \text{ V}$ ) is shown for  
clarity because carrier injection effects start to distort the  $C-V$   
relation in forward bias.

**5.1. Elemental Diffusion from the Buffer Layer.** All  
samples with the CdS or Zn(O,S) buffer layer show the well-  
known pronounced doping gradient already observed in  
Section 3. If we use a thin  $\text{MgF}_2$  layer (blue diamonds in  
Figure 5) instead of the typical buffer/window stack, we obtain





**Figure 5.** Apparent dopant concentration  $N$  at  $T = 300$  K vs apparent depth  $w$  for different buffer/window combinations mentioned in the graph. Only reverse bias ( $V < 0$  V) is shown for clarity.

680 a much higher apparent dopant concentration close to  $10^{17}$   
 681  $\text{cm}^{-3}$ , which is comparable to the (in-grain) free carrier  
 682 concentration obtained by Hall measurements<sup>40</sup> of comparable  
 683 absorbers. Accordingly,  $C-V$  measurements indeed yield the  
 684 correct absorber dopant concentration for this particular  
 685 sample (covered with  $\text{MgF}_2$ ) and the doping gradients  
 686 observed for CdS and Zn(O,S) devices must either be real  
 687 or a measurement artifact caused by the different buffer/  
 688 window stacks.

689 If the experimental doping gradient was indeed an artifact  
 690 related to the different buffer/window stack compared to a  
 691  $\text{MgF}_2$  layer, it should disappear in sample 5 containing an  
 692 identical  $\text{MgF}_2$  layer on the etched device. In contrast, we  
 693 observe a pronounced doping gradient (green triangles in  
 694 Figure 5) even after replacing the buffer/window stack with  
 695  $\text{MgF}_2$ . The doping profile in this case is quite different from  
 696 the CdS and Zn(O,S) devices but this might be in part related  
 697 to the etching process; on the basis of SIMS profiles, the  
 698 etched absorber appears to be 100–200 nm thinner than the  
 699 initial absorber. This value is difficult to determine with any  
 700 certainty and is likely insignificant compared to local thickness  
 701 variations. Nevertheless, etching in HCl might indeed have  
 702 removed at least some part of the original absorber surface.  
 703 One might argue that the thickness of the intrinsic ZnO layer  
 704 in the window stack could contribute to the apparent depth  
 705 and thus explain the shift between doping profiles of samples  
 706 with and without the  $i\text{-ZnO}$  layer. This is not the case in our  
 707 study because we have separated the junction capacitance and  
 708 any capacitive contributions of intrinsic interlayers from the  
 709 frequency-dependent impedance spectrum. The impact of the  
 710  $i\text{-ZnO}$  layers on the apparent depth would anyway be small at  
 711 300 K because of their high conductivity, which is also  
 712 apparent from the temperature range of the main capacitance  
 713 step associated with the buffer layer in Figure 1.

714 **5.2. Cadmium Versus Zinc.** By comparing both devices  
 715 with the  $\text{MgF}_2$  layer, we have established that the typical  
 716 dopant gradient observed in  $C-V$  measurements of CIGS  
 717 devices is indeed located within the absorber and not related to  
 718 the presence of the buffer/window stack. This conclusion is  
 719 furthermore consistent with the PL results discussed in Section  
 720 6 below. We obtain similar doping profiles for devices with  
 721 CdS or Zn(O,S) buffer layers, although Zn(O,S) is nominally  
 722 free of Cd. Note that we do detect small traces of Cd in  
 723 absorbers covered with Zn(O,S), presumably due to the  
 724 contamination of the equipment used for CBD. Migration of  
 725 Zn into the absorber would likely also reduce the surface-near  
 726 net dopant concentration because substitutional Zn-on-Cu

(Zn<sub>Cu</sub>) is predicted to be a donor in CIGS as well, albeit  
 energetically somewhat deeper than  $\text{Cd}_{\text{Cu}}$ .<sup>51</sup>

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 728  
 729 Compared to CdS, the doping gradient in the absorber with  
 the Zn(O,S) buffer layer appears to be steeper in Figure 5,  
 which results in a higher net dopant concentration deep within  
 the bulk. In some cases, (not shown here) we even obtain  
 apparent doping profiles approaching the bulk dopant  
 concentration close to  $10^{17} \text{ cm}^{-3}$  at large reverse bias for  
 devices containing a Zn(O,S) buffer layer. These differences  
 between CdS and Zn(O,S) buffered devices are consistent with  
 the literature data of the diffusion coefficients of Cd and Zn in  
 CIGS.<sup>60,61</sup> The diffusion coefficient of Cd is larger than that of  
 Zn in the relevant temperature range and we expect a deeper  
 penetration of Cd into the CIGS absorber, whereas Zn is more  
 confined to the surface-near region of the absorber.

741  
 742 Although this trend agrees with the relative magnitudes of  
 the respective diffusion coefficients of Cd and Zn, the apparent  
 penetration depth of several hundreds of nanometers suggested  
 by Figure 5 is much larger than expected. Extrapolating the  
 reported experimental diffusion coefficients<sup>60,61</sup> to room  
 temperature, the penetration depth of both Cd and Zn in  
 CIGS should not exceed a few nanometers. A few caveats have  
 to be taken into consideration, however.

- Irregularities in the diffusion processes have been reported in these studies,<sup>60,61</sup> and copper vacancies and grain boundaries also enhance the diffusion process.<sup>62–64</sup>
- During rf-sputtering of the ZnO window layer stack, the absorber layer is exposed to elevated temperatures and the sputtering plasma. Interdiffusion might be significantly enhanced under these conditions. Already at 100 °C, for example, Cd and Zn diffusion coefficients are 3–4 orders of magnitude higher compared to their room-temperature values, which increases the penetration depth by roughly a factor of 100. At 200 °C, the penetration depth would even be 3 orders of magnitude higher compared to room temperature.
- Small quantities below 10 ppm of electrically active Cd or Zn might already be sufficient to fully compensate the bulk net acceptor concentration of  $10^{17} \text{ cm}^{-3}$ .

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**5.3. Complementary Electrical Measurement Techniques.** Such small quantities of Cd or Zn prove difficult to detect with sufficient precision in CIGS thin-film devices, even by SIMS measurements, but their electronic effect should be readily detectable in Hall measurements. Nevertheless, we did not observe any effect of CdS deposition on the in-grain carrier concentration in our earlier Hall experiments.<sup>19,40</sup> A standard Hall measurement probes the full cross section of the sample and is thus less sensitive to the near-surface doping than  $C-V$  measurements. Accordingly, the initial interdiffusion restricted to a near-surface layer might have gone undetected because of the high conductivity of the unaffected part of the highly-doped CIGS layer. We expect a more drastic change of the doping profile after some time because the Cd diffusion appears to proceed noticeably even at room temperature.<sup>40</sup> We have thus attempted to repeat Hall measurement of the same sample after storage for 18 months in vacuum. The resolution of these measurements is insufficient to obtain reliable results for the majority carrier concentration and mobility, in large part because of a strong increase of the sheet resistance over time. The absorber layer initially had an average resistivity of approximately  $35 \Omega \text{ cm}$  at  $T = 270$  K, which increased to  $60 \Omega$

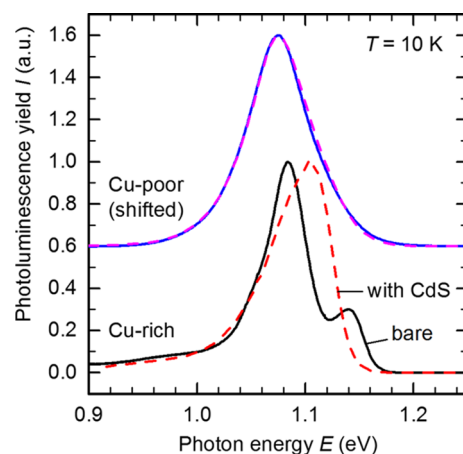
789 cm after CdS deposition mainly due to increased band bending  
790 at the grain boundaries.<sup>40</sup> After 18 months of storage in  
791 vacuum, we measure a resistivity of 165  $\Omega$  cm, which clearly  
792 indicates that the transport properties of the CdS-coated  
793 absorber have changed with time even when stored at room  
794 temperature. Although part of the increase in resistivity might  
795 again be due to changes of the grain boundary potential, these  
796 results would also be consistent with a substantial decrease of  
797 net dopant concentration in parts of the absorber layer.

798 In the literature, cross sections of CIGS devices have been  
799 studied by spreading resistance and electron beam induced  
800 current (EBIC) techniques, see, for example, refs.<sup>65,66</sup> to map  
801 the majority carrier concentration and current collection by the  
802 SCR, respectively. This allows in principle to reconstruct the  
803 laterally and depth-resolved local dopant concentration within  
804 the absorber. Spreading resistance maps recorded at flat band  
805 conditions in ref 65 revealed a highly resistive near-surface  
806 layer, which has been attributed to type-inversion because of  
807 Cd diffusion into the absorber. This effect was far more  
808 pronounced in Cu-depleted samples, indicating that Cd  
809 diffusion indeed preferentially proceeds via Cu vacancies. It  
810 is worth pointing out, however, that this study only found a  
811 low doping efficiency of Cd in CIGS because the surface-near  
812 Cd-doped n-type layer was much lower doped than the p-type  
813 absorber. Such a low doping efficiency, however, only affects  
814 the formation of an inverted n-doped layer, whereas Cd is  
815 apparently still able to efficiently compensate the p-type  
816 absorber doping, leading to a doping gradient. This suggests  
817 that the donor state associated with the Cd<sub>Cu</sub> defect  
818 energetically lies fairly deep below the conduction band.  
819 Recent EBIC measurements<sup>67</sup> revealed that the magnitude and  
820 fluctuations of the SCR width within the p-type absorber  
821 strongly depend on the buffer and window layers used in the  
822 device stack, which also supports interdiffusion processes  
823 between these layers and the CIGS absorber to have a  
824 noticeable impact on the electronic bulk properties. Both  
825 spreading resistance and EBIC measurements show that the  
826 net dopant concentration in the absorber might differ  
827 significantly between different grains.<sup>65–67</sup> This effect cannot  
828 be resolved by macroscopic C–V measurements, which  
829 average over many grains but might contribute to differences  
830 between (perpendicular) C–V and (lateral) Hall measure-  
831 ments. Accordingly, although all of these results from different  
832 electrical measurements support a reduced net doping  
833 concentration near the p/n-junction because of interdiffusion  
834 processes between the buffer or window layer and absorber,  
835 the actual bulk doping concentration deep within the absorber  
836 cannot be determined reliably by C–V measurements and  
837 furthermore might vary significantly with lateral position.

## 6. ROLE OF CADMIUM STUDIED BY PL

838 PL experiments on bare and CdS-coated absorbers provide  
839 further evidence for fast Cd in-diffusion into the surface-near  
840 regions of the CIGS absorber. CIGS absorbers with different  
841 copper contents show distinct differences in their respective  
842 low-temperature PL spectra because of the different  
843 compensation ratios  $N_D/N_A$ , that is, the ratio of compensating  
844 donor concentration to the total acceptor concentration.<sup>68,69</sup> A  
845 high compensation ratio leads to local fluctuations of the  
846 electrostatic potential, thus broadening the PL emission peaks  
847 and resulting in a stronger shift of the PL peaks with increasing  
848 excitation intensity. Because of their high concentration of  
849 native point defects, Cu-poor absorbers with  $[\text{Cu}]/([\text{In}] +$

$[\text{Ga}]) < 1$  usually exhibit only a single broad, asymmetric PL 850  
emission peak. In contrast, individual donor–acceptor-pair and 851  
excitonic transitions can be resolved for nearly stoichiometric 852  
absorbers grown under Cu excess (“Cu-rich”).<sup>68,69</sup> Figure 6 853 854

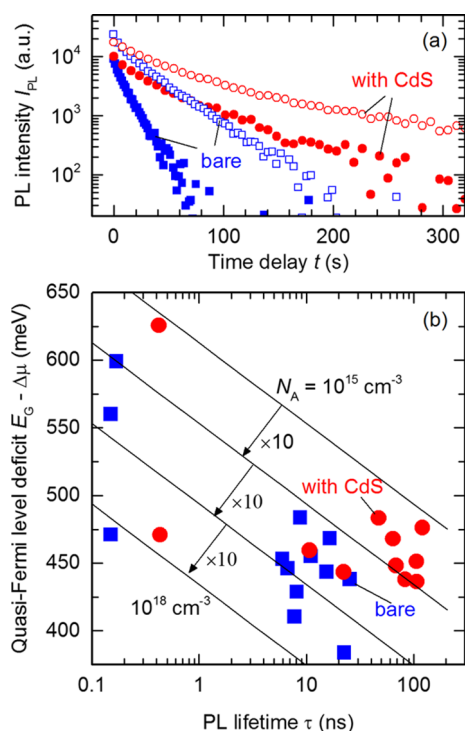


**Figure 6.** PL spectra recorded at  $T = 10$  K for Cu-rich and Cu-poor (data shifted vertically by +0.6 for clarity) absorbers before (solid lines) and directly after (dashed lines) CBD of a CdS layer.

shows the low-temperature ( $T = 10$  K) PL spectra of bare Cu- 854  
poor and Cu-rich CIGS absorbers before (solid lines) and 855  
directly after (dashed lines) depositing a standard CdS layer by 856  
CBD. The Cu-rich absorber had been etched in a KCN 857  
solution prior to the PL experiment to remove Cu<sub>x</sub>Se 858  
secondary phases developed under Cu-rich growth conditions. 859

For the bare Cu-rich absorber, we initially clearly resolve 860  
several individual transitions, which are broadened into a single 861  
asymmetric peak after CdS deposition. Such an asymmetric 862  
broadening is similarly attributed to an increased compensa- 863  
tion ratio within the absorber, that is, an increase in donor 864  
concentration or a decrease in acceptor concentration upon 865  
CdS deposition. In addition, the main peak at 1.08 eV shifts by 866  
3 meV/decade with increasing excitation intensity for the bare 867  
Cu-rich absorber, indicating a low degree of compensation. 868  
After CdS deposition, this peak shifts by more than 12 meV/ 869  
decade, typically related to a strong electrostatic fluctuation 870  
caused by compensating donors.<sup>68</sup> It should be noted that 871  
these measurements are performed at low temperatures, where 872  
the free carrier mobility is low.<sup>19,40,70</sup> This means that the PL 873  
emission stems predominantly from the region where 874  
absorption of the excitation laser takes place, that is, from 875  
the first  $\sim 100$  nm near the surface. Thus, by adding a CdS 876  
layer onto a Cu-rich absorber, we observe that its 877  
compensation is increased, in agreement with Cd in-diffusion, 878  
which results in a lower doping level near the surface. The bare 879  
Cu-poor absorber only shows a single broad PL peak, which is 880  
only slightly broadened upon CdS deposition. This can be 881  
attributed to the already high compensation of the bare 882  
absorber in the Cu-poor case, and any further increase of the 883  
compensation ratio would not strongly alter the peak shape 884  
any further. 885

Further evidence for a reduced doping level after CdS 886  
deposition comes from time-resolved PL measurements on 887  
polycrystalline CIGS absorbers at room temperature. Figure 7a 888 889  
shows exemplary time-resolved PL measurements of two 889  
different sets of bare and CdS-coated Cu-poor absorbers, 890  
which demonstrate that the experimental PL decay curves are 891



**Figure 7.** (a) Time-resolved PL measurements of two different Cu-poor absorbers (open and closed symbols, respectively): bare absorber (blue) and with CdS (red). (b) Quasi-Fermi level splitting deficit  $E_G - \Delta\mu$  as a function of PL lifetime  $\tau$  for bare (blue squares) and CdS-covered (red circles) CIGS absorbers. The solid lines represent calculated trends according to eq 7, where the dopant concentration  $N_A$  is each time increased by 1 order of magnitude from approximately  $10^{15} \text{ cm}^{-3}$  (top) to  $10^{18} \text{ cm}^{-3}$  (bottom).

not monoexponential. We fit the experimental data with the sum of three exponential decays  $I_{PL}(t) = \sum_i A_i \exp(-t/\tau_i)$  and estimate a mean PL lifetime  $\tau$  as weighted average  $\tau = \sum_i A_i \tau_i / \sum_i A_i$ . These results are similar to a single exponential fit in an intermediate time range but remove the ambiguity of having to manually define a fitting range.

We compare the quasi-Fermi level splitting  $\Delta\mu$  and PL lifetime  $\tau$  before and after CdS deposition. Because  $\Delta\mu$  is proportional to the band gap  $E_G$  of the absorber, we rather discuss the quasi-Fermi level splitting deficit  $E_G - \Delta\mu$ , that is, the difference between band gap and quasi-Fermi level splitting. Besides the band gap, the quasi-Fermi level splitting also depends on the excitation, which is kept constant in all measurements, on the amount of nonradiative recombination described by the reduced PL lifetime  $\tau$ , and on the doping density  $N_A$ .<sup>71</sup> We use a simple model to relate lifetime  $\tau$  and quasi-Fermi level splitting  $\Delta\mu$

$$\Delta\mu = kT \ln\left(\frac{N_A \Delta n}{n_i^2}\right) = kT \ln\left[\frac{N_A \alpha j_{ph} \tau}{N_C N_V \exp\left(-\frac{E_G}{kT}\right)}\right] \quad (6)$$

where  $k$  is Boltzmann constant,  $T$  is temperature,  $N_A$  is net dopant concentration,  $\Delta n$  is the excess carrier concentration,  $n_i$  is the intrinsic carrier concentration,  $\alpha$  is the inverse absorption length,  $j_{ph}$  is the photon flux of the excitation,  $N_C$  and  $N_V$  are the effective density of states of the conduction and valence bands, respectively, and  $E_G$  is the band gap. Equation 6 is only valid in low excitation, which was ensured by the experimental

conditions. We obtain an expression for the quasi-Fermi level splitting deficit by rearranging eq 6

$$E_G - \Delta\mu = kT \ln\left[\frac{C}{\tau N_A}\right] \quad (7)$$

where the constant  $C = (N_C N_V) / (\alpha j_{ph})$  in the numerator has the same value for all samples in our study. This deficit is thus higher for increased nonradiative recombination, that is, for lower lifetime, but also increases for lower dopant concentrations.

Figure 7 shows experimental values of the quasi-Fermi level splitting deficit  $E_G - \Delta\mu$  as a function of PL lifetime  $\tau$  for bare and CdS-covered absorbers. In both cases, the low lifetimes below 1 ns are observed for Cu-rich absorbers and the higher ones for Cu-poor CIGS. The quasi-Fermi level splitting  $\Delta\mu$  of freshly etched or freshly prepared absorbers is identical within error to the one on absorbers covered with CdS.<sup>72</sup> In contrast to the quasi-Fermi level splitting, which essentially remained unchanged, the carrier lifetime determined by time-resolved PL measurements at room temperature changes considerably between freshly etched and CdS-covered absorbers. Various bare absorbers measured directly after etching show average lifetimes between 5 and 20 ns (Cu-poor) and around 0.1 ns (Cu-rich). PL lifetimes of the same samples with a CdS buffer vary between 10 and 100 ns (Cu-poor) or around 0.5 ns (Cu-rich).

A similar quasi-Fermi level splitting within the same absorber, despite the pronounced differences in lifetime, is best described by a change in dopant concentration. For the constant  $C$  in eq 7, we estimate a value of  $C \approx 1.6 \times 10^{16} \text{ s/cm}^3$  for our samples, assuming 1 sun illumination,  $N_C = 7 \times 10^{17} \text{ cm}^{-3}$  and  $N_V = 1.5 \times 10^{19} \text{ cm}^{-3}$  corresponding to effective electron and hole masses of 0.09 and 1.0, respectively, and assuming that  $\alpha$  is given by the inverse absorber thickness at room temperature. Note that the factor  $\alpha$  in eqs 6 and 7 converts the incident photon area density to a volume density of photoexcited carriers. Because excess carriers initially generated near the absorber surface redistribute throughout the absorber in a quasi-static PL measurement, the appropriate value of  $\alpha$  will be smaller than the absorption coefficient in CIGS. Solid lines in Figure 7 show calculated relations between quasi-Fermi level splitting deficit and lifetime calculated from eq 7 for different dopant concentrations. From top to bottom, the dopant concentration increases from approximately  $N_A = 10^{15}$  to  $10^{18} \text{ cm}^{-3}$  by 1 order of magnitude between two calculations. As can be seen in Figure 7, most of the measurements on CdS-covered absorbers (red circles) can be described by doping levels around approximately  $10^{16} \text{ cm}^{-3}$ , about 1 order of magnitude lower than  $N_A \approx 10^{17} \text{ cm}^{-3}$  of bare absorbers (blue squares). The exact numbers depend on the assumptions made for  $\alpha$ ,  $N_C$ , and  $N_V$ , but relative trends do not depend on these assumptions. Thus, also the time-dependent PL measurements indicate a reduced doping of the front part of the absorber, which is accessible by PL, after the CdS deposition.

Our PL results thus support the model that substantial Cd in-diffusion could proceed quickly even at moderate temperatures of 70 °C or below during CdS deposition. Note that, in addition, Cu from the absorber might diffuse into the CdS layer, thus representing an intermixing of the CdS and CIGS layers at the interface.

## 7. DISCUSSION

The electrical characterization of thin-film solar cells by means of capacitance–voltage ( $C-V$ ) measurements was addressed with particular focus on the dopant concentration of the absorber layer in CIGS solar cells. We specifically focused on discrepancies between  $C-V$  and Hall measurements and on the correct interpretation of depth-dependent doping profiles determined by  $C-V$  profiling, which show an increasing apparent net acceptor concentration with depth.

The time-dependence of the device capacitance recorded at different bias voltages showed a clear saturation behavior, indicating a noticeable effect of “slow” defect states with characteristic time constants of seconds or even minutes, and thus well below the frequency range accessible in thermal admittance spectroscopy. Although these defect states do influence the apparent doping profile, they mainly act to expand the SCR width and only have a minor effect on the doping gradient. The ideal deep defect-free SCR capacitance estimated from the experimental capacitance transients accordingly still indicates a reduced net dopant concentration near the buffer/absorber interface. A depth-dependent doping profile is typically analyzed by calculating the local slope of a Mott–Schottky plot  $C^{-2}(V)$ . Although this produces the correct apparent doping profile as a function of apparent depth for an arbitrary device, it does not provide any further insight into the physical origin of such a profile. Here, it is useful to additionally consider different exponents  $x$  for  $C^{-x}(V)$ ; the inverse squared capacitance  $C^{-2}(V)$  yields a straight line as function of voltage for constant dopant concentrations, whereas the inverse cube capacitance  $C^{-3}(V)$  yields a straight line for linearly graded doping profiles. We showed that the ideal deep defect-free SCR capacitance estimated from the capacitance transients indeed perfectly follows the model of a linearly graded junction for our devices. On the basis of this observation, the true dopant concentration deep within the absorber bulk might indeed be severely underestimated by conventional  $C-V$  analysis, both due to the correction factor in the model for a nonabrupt junction and due to a reduced net doping within the SCR.

Our model of a modified dopant concentration in devices including a buffer layer was verified by comparing different buffer layers deposited onto the same absorber. Although the typical “U”-shaped apparent doping profile was found for both CdS and Zn(O,S) buffer layers with the  $i$ -ZnO/ZnO:Al window layer, this effect was completely absent when using a thin  $\text{MgF}_2$  layer instead. The apparent dopant concentration close to  $10^{17} \text{ cm}^{-3}$  for the  $\text{MgF}_2$ -covered absorber in fact agrees with free carrier concentrations previously obtained by Hall measurements on similar absorbers. We showed that this result is not an artifact because of parasitic effects of the buffer/window layers on the capacitance measurement by etching off the CdS/ZnO buffer/window stack and subsequently covering the etched absorber with  $\text{MgF}_2$ . We still found a pronounced doping gradient in this sample, indicating that the deposition of the initial buffer/window stack prior to the etching led to a physical change of the absorber near the surface. We expect these changes to be related to Cd or Zn diffusion from the buffer layer into the absorber, which could increase the donor concentration ( $\text{Cd}_{\text{Cu}}$ ,  $\text{Zn}_{\text{Cu}}$ ) and reduce the acceptor concentration ( $V_{\text{Cu}}$ ) in the CIGS absorber close to the interface. This diffusion proceeds even at room temperature and the net dopant concentration of a given sample will change

over time.<sup>40</sup> Although we consider Cd and Zn incorporation to most probably occur via vacancies in the copper lattice, other mechanisms or incorporation on other lattice sites might equally play a role and might also explain differences between different buffer layer materials.

Our results from electrical characterization were shown to be consistent with PL studies of bare absorbers and absorbers covered with CdS. Deposition of CdS increases potential fluctuations in the absorber, in particular for CIGS absorbers grown under Cu excess, which initially are virtually free of potential fluctuations. Furthermore, the relation between quasi-Fermi level splitting and PL lifetime could only be modeled by a significantly reduced dopant concentration in absorbers covered with CdS compared to bare absorbers. The PL experiments are thus in good agreement with a substantial reduction in near-surface net dopant concentration caused by increased donor/acceptor compensation, upon deposition of a CdS layer.

## 8. CONCLUSIONS

Our results demonstrate that interdiffusion at the absorber/buffer interface of CIGS thin-film solar cells is a critical factor to consider in the correct interpretation of doping profiles obtained from  $C-V$  analysis. The net dopant concentration near the absorber/buffer interface is significantly reduced in devices with Cd- or Zn-containing buffer layer compared to bare absorbers. On the one hand, the true bulk dopant concentration deep within the absorber might thus be far larger than previously expected. On the other hand, the choice of the buffer layer material could be of particular importance by determining the deep and shallow defect concentrations within the SCR, which is the most crucial component of a typical solar cell.

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#### Notes

The authors declare no competing financial interest.

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